

IN THE SPECIFICATION

Please amend the specification as follows:

Replace the paragraph spanning pages 9-10, between page 9, line 28, and page 10, line 3 of the specification with the following:

Figs. 3A-C schematically show a manufacturing step of the camera module according to the invention. Fig. 3A is a side elevation which shows, in addition to the elements that are shown in Fig. 2A, the bonding wires 116 that connect the bond pads 115 (not shown) to the pads 117 (likewise not shown) on the substrate 105. Fig. 3B is a top plan view which shows, in addition to the elements that are shown in Fig. 2B, the bonding wires 116 that connect the bond pads 115 to the ~~pads 116~~ pads 117 on the substrate. Fig. 3C is a schematic, perspective view of the solid-state image sensor 113 provided with the image pick-up section 114, which is present on the substrate 105, in which the bond pads 115 of the solid-state image sensor 113 are connected to the pads 117

on the substrate by means of the bonding wires 116.

Replace the paragraph spanning pages 12-13, between page 12, line 29, and page 13, line 3 of the specification with the following:

Figs. 7A-C schematically show a further manufacturing step of the camera module according to the invention. Fig. 7A is a side elevation which shows, in addition to the elements that are shown in Fig. 6A, the glob top material 103 which abuts both the outer side of the holder 102 and the substrate 105, and which screens and strengthens the joint between the two. Said glob top material also strengthens the connection between the holder 102 and the substrate 105. Fig. 7B is a top plan view which shows, in addition to the elements that are shown in Fig. 6A, the glob top material 103. Fig. 7C is a perspective view which shows, in addition to the elements that are shown ~~in Figs.~~ in Fig. 6C, the glob top material 103 as an edge that extends around the holder 102.